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LCD and Camera EMI Filter Array with ESD Protection

CM1430

Features

- Four, six and eight channels of EMI filtering with integrated ESD protection
- Pi-style EMI filters in a capacitor-resistor-capacitor (C-R-C) network
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Greater than 20dB attenuation (typical) at 1 GHz
- TDFN package with 0.40mm lead pitch:
  - 4-ch. = 8-lead TDFN
  - 6-ch. = 12-lead TDFN
  - 8-ch. = 16-lead TDFN
- Tiny TDFN package size:
  - 8-lead: 1.7mm x 1.35mm
  - 12-lead: 2.5mm x 1.35mm
  - 16-lead: 3.3mm x 1.35mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free version available

Applications

- LCD and Camera data lines in mobile handsets
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- Wireless handsets
- Handheld PCs/PDAs
- LCD and camera modules

Product Description

The CM1430 is a family of pi-style EMI filter arrays with ESD protection, which integrates four, six and eight filters (C-R-C) in small form factor TDFN 0.40mm pitch packages. The CM1430 has component values of 8.5pF-100Ω-8.5pF per channel. The CM1430 has a cut-off frequency of 200MHz and can be used in applications with data rates up to 80Mbps. The parts include ESD diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD protection diodes safely dissipate ESD strikes of ±15kV, well beyond the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30kV.

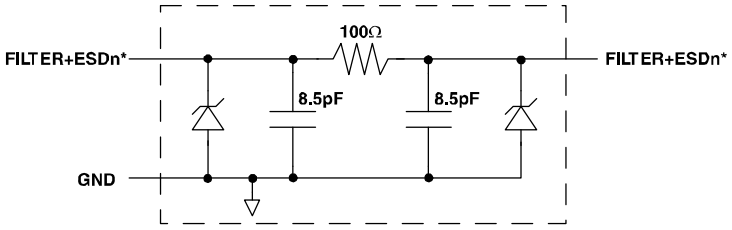
These devices are particularly well-suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of their small package and easy-to-use pin assignments. In particular, the CM1430 is ideal for EMI filtering and protecting data and control lines for the I/O data ports, LCD display and camera interface in mobile handsets.

The CM1430 is housed in space-saving, low-profile 8-,12- and 16-lead TDFN packages with a 0.4mm pitch and is available with lead-free finishing. This new small TDFN package provides up to 42% board space savings vs. the 0.50mm pitch TDFN packages.

April 2010 Rev. 2

Publication Order Number:
CM1430/D

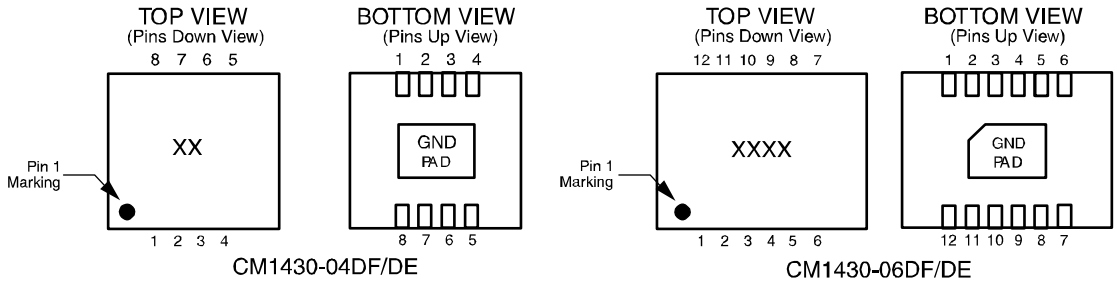
Electrical Schematic



1 of 4, 6 or 8 EMI/RFI Filter Channels with Integrated ESD Protection

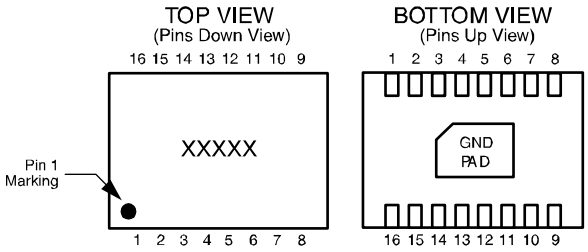
*** See Package/Pinout Diagram for expanded pin information.**

PACKAGE / PINOUT DIAGRAMS



CM1430-04DF/DE
8 Lead TDFN Package

CM1430-06DF/DE
12 Lead TDFN Package



CM1430-08DF/DE
16 Lead TDFN Package

Notes:
1) These drawings are not to scale.

PIN DESCRIPTIONS										
DEVICE PIN(s)			NAME	DESCRIPTION		DEVICE PIN(s)			NAME	DESCRIPTION
-04	-06	-08				-04	-06	-08		
1	1	1	FILTER1	Filter + ESD Channel 1		8	12	16	FILTER1	Filter + ESD Channel 1
2	2	2	FILTER2	Filter + ESD Channel 2		7	11	15	FILTER2	Filter + ESD Channel 2
3	3	3	FILTER3	Filter + ESD Channel 3		6	10	14	FILTER3	Filter + ESD Channel 3
4	4	4	FILTER4	Filter + ESD Channel 4		5	9	13	FILTER4	Filter + ESD Channel 4
	5	5	FILTER5	Filter + ESD Channel 5			8	12	FILTER5	Filter + ESD Channel 5
	6	6	FILTER6	Filter + ESD Channel 6			7	11	FILTER6	Filter + ESD Channel 6
		7	FILTER7	Filter + ESD Channel 7				10	FILTER7	Filter + ESD Channel 7
		8	FILTER8	Filter + ESD Channel 8				9	FILTER8	Filter + ESD Channel 8
GND PAD			GND	Device Ground						

Ordering Information

PART NUMBERING INFORMATION					
		Standard Finish		Lead-free Finish	
Pins	Package	Ordering Part Number[1]	Part Marking	Ordering Part Number[1]	Part Marking
8	TDFN-8	CM1430-04DF	VF	CM1430-04DE	VE
12	TDFN-12	CM1430-06DF	N30F	CM1430-06DE	N30E
16	TDFN-16	CM1430-08DF	N308F	CM1430-08DE	N308E

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS		
PARAMETER	RATING	UNITS
Storage Temperature Range	-65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	500	mW

STANDARD OPERATING CONDITIONS

PARAMETER	RATING	UNITS
Operating Temperature Range	-40 to +85	°C

ELECTRICAL OPERATING CHARACTERISTICS (SEE NOTE1)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
R	Resistance		80	100	120	Ω
C_{TOTAL}	Total Channel Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	14	17	22	pF
C	Capacitance C1	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	7	8.5	11	pF
V_{DIODE}	Standoff Voltage	I_{DIODE}=10μA		6.0		V
I_{LEAK}	Diode Leakage Current (reverse bias)	V_{DIODE}=+3.3V		0.1	1.0	μA
V_{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	 I_{LOAD} = 10mA I_{LOAD} = -10mA	 5.6 -1.5	 6.8 -0.8	 9.0 -0.4	 V V
V_{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	Note 2	 30 15			 kV kV
R_{DYN}	Dynamic Resistance Positive Negative			 2.3 0.9		 Ω Ω
f_C	Cut-off Frequency Z_{SOURCE}=50Ω, Z_{LOAD}=50Ω	Channel R = 100Ω, Channel C = 8.5pF		200		MHz

Note 1: T_A=25°C unless otherwise specified.
Note 2: ESD applied to input and output pins with respect to GND, one at a time.

Performance Information

Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

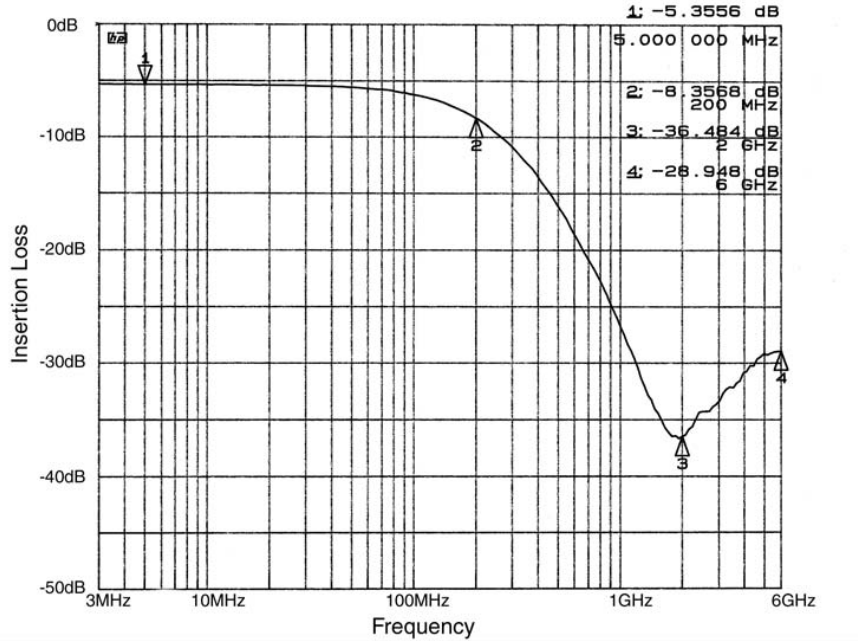


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND)

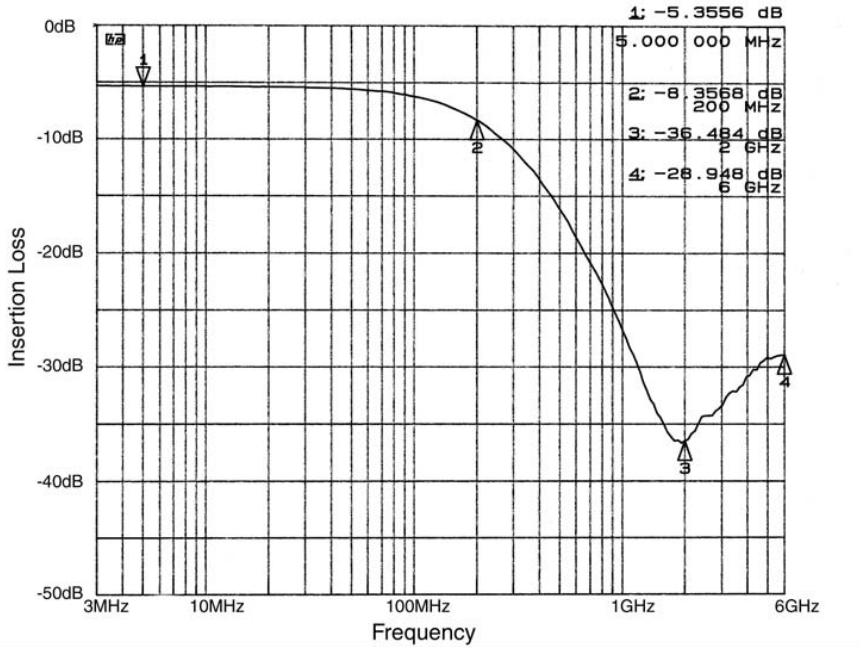


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND)

Performance Information (cont'd)

Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

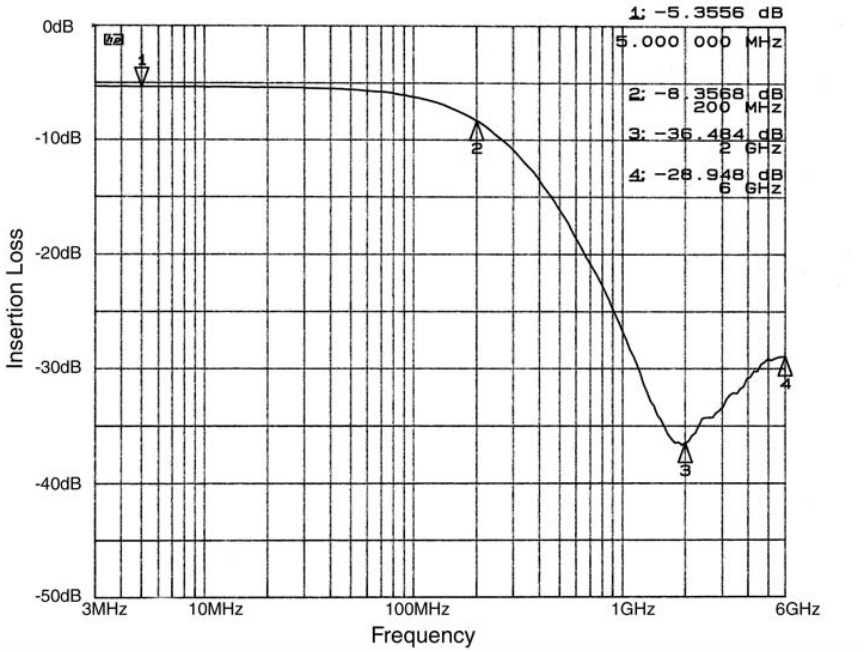


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND)

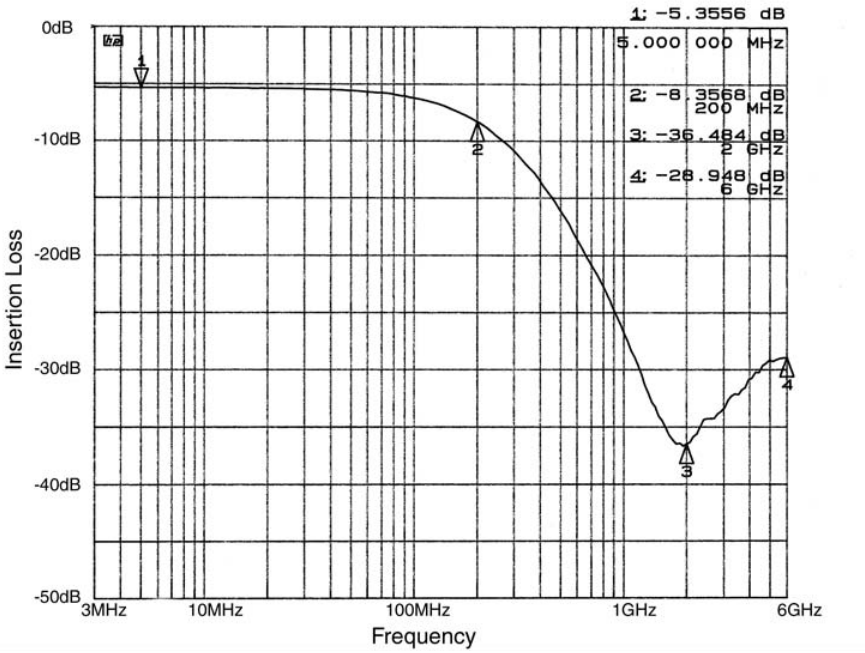


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND)

Performance Information (cont'd)

Typical Diode Capacitance vs. Input Voltage

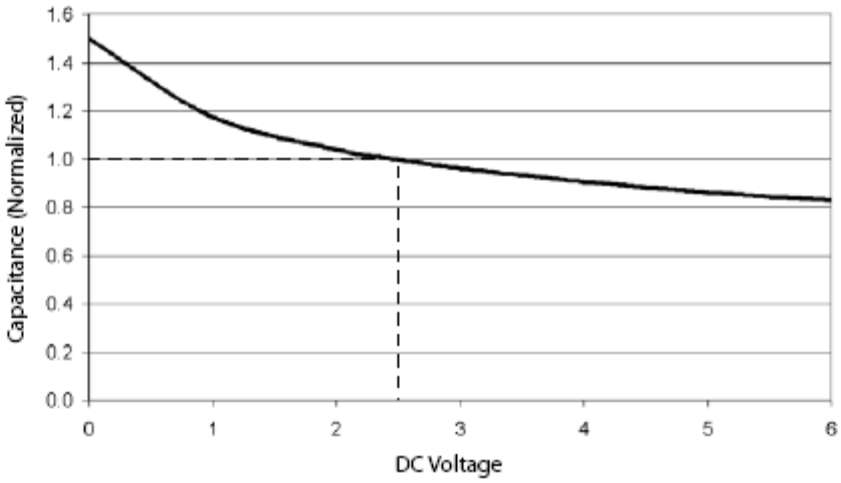


Figure 5. Filter Capacitance vs. Input Voltage (normalized to capacitance at 2.5VDC and 25°C)

Mechanical Details

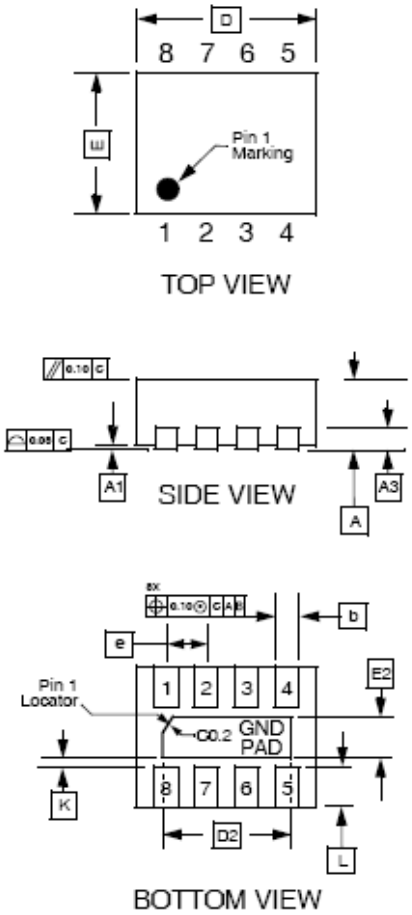
CM1430-04DF/DE Mechanical Specifications

Dimensions for the CM1430-04DF/DE suplied in a 8-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-8, see the California Micro Devices TDFN Package Information document.

PACKAGE DIMENSIONS						
Package	TDFN					
JEDEC No.	MO-229C					
Leads	8					
Dim.	**Millimeters**			**Inches**		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	1.60	1.70	1.80	0.063	0.067	0.071
D2	1.10	1.20	1.30	0.043	0.047	0.051
E	1.25	1.35	1.45	0.049	0.053	0.057
E2	0.30	0.40	0.50	0.012	0.016	0.020
e	0.40 BSC			0.016 BSC		
K	0.20			0.008		
L	0.15	0.25	0.35	0.006	0.010	0.014
# per tape and reel	3000 pieces					
Controlling dimension: millimeters						

This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Mechanical Package Diagrams



Dimensions for 8-Lead, 0.4mm pitch TDFN package

Mechanical Details (cont'd)

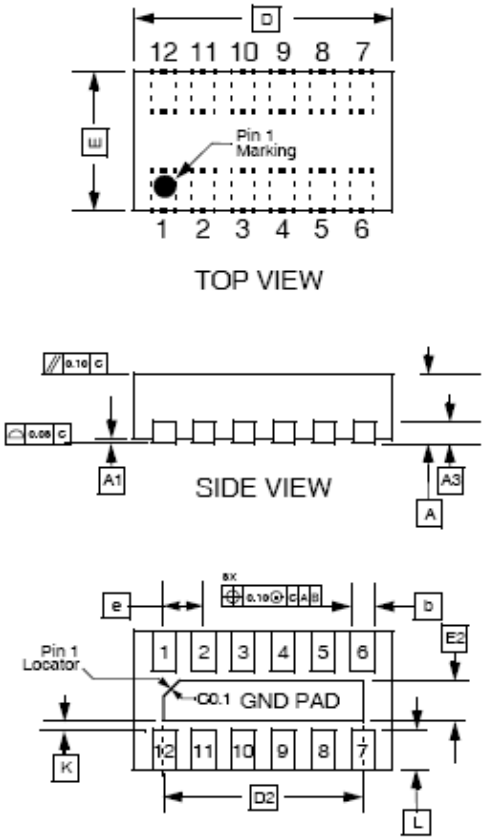
CM1430-06DF/DE Mechanical Specifications

Dimensions for the CM1430-06DF/DE suplied in a 12-lead, 0.4mm pitch TDFN package are presented below.

PACKAGE DIMENSIONS						
Package	TDFN					
JEDEC No.	MO-229C					
Leads	12					
Dim.	**Millimeters**			**Inches**		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	2.40	2.50	2.60	0.094	0.098	0.102
D2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.25	1.35	1.45	0.049	0.053	0.057
E2	0.30	0.40	0.50	0.012	0.016	0.020
e	0.40 BSC			0.016 BSC		
K	0.20			0.008		
L	0.15	0.25	0.35	0.006	0.010	0.014
# per tape and reel	3000 pieces					
Controlling dimension: millimeters						

This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Mechanical Package Diagrams



Dimensions for 12-Lead, 0.4mm pitch TDFN package

Mechanical Details (cont'd)

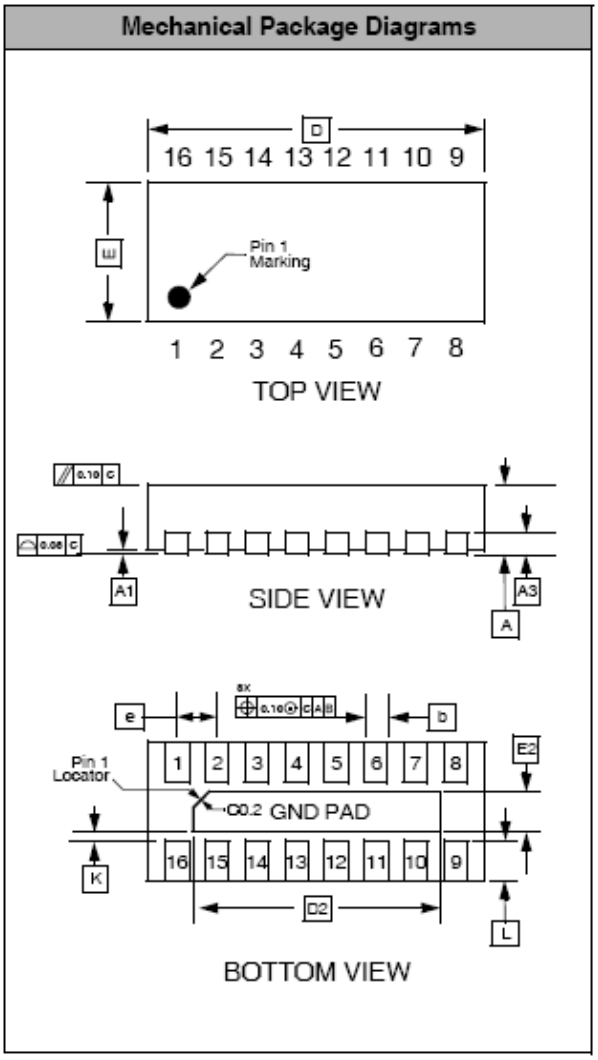
CM1430-08DF/DE Mechanical Specifications

Dimensions for the CM1430-08DF/DE supplied in a 16-lead, 0.4mm pitch TDFN package are presented below. For complete information on the TDFN-16, see the California Micro Devices TDFN Package Information document.

PACKAGE DIMENSIONS						
Package	TDFN					
JEDEC No.	MO-229C					
Leads	16					
Dim.	**Millimeters**			**Inches**		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.200 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	3.20	3.30	3.40	0.126	0.130	0.134
D2	2.70	2.80	2.90	0.106	0.110	0.114
E	1.25	1.35	1.45	0.049	0.053	0.057
E2	0.30	0.40	0.50	0.012	0.016	0.020
e	0.40 BSC			0.016 BSC		
K	0.20			0.008		
L	0.15	0.25	0.35	0.006	0.010	0.014
# per tape and reel	3000 pieces					
Controlling dimension: millimeters						

This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Mechanical Package Diagrams



Dimensions for 16-Lead, 0.4mm pitch TDFN package

PUBLICATION ORDERING INFORMATION

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